



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of

Alexander T. SCHWARM et al.

Serial No. 10/632,107

Filed: August 1, 2003

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Group Art Unit: 2812

Examiner:

For: METHOD, SYSTEM, AND MEDIUM FOR HANDLING MISREPRESENTATIVE
METROLOGY DATA WITHIN AN ADVANCED PROCESS CONTROL SYSTEM

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

WILMER CUTLER PICKERING HALE AND DORR LLP

A handwritten signature in black ink, appearing to read "SMA Alter", is written over the printed name.

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Date: 6/16/04

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 7720/FPS/MMCS/APC		SERIAL NO. 10/632,107	
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				FILING DATE August 1, 2003		GROUP 2812	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
	4,207,520	06/10/80	Flora et al.			04/06/78	
	4,209,744	06/24/80	Gerasimov et al.			03/27/78	
	4,302,721	11/24/81	Urbanek et al.			05/15/79	
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	5,236,868	08/17/93	Nulman			04/20/90	
	5,260,868	11/09/93	Gupta et al.			10/15/91	
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	5,283,141	02/01/94	Yoon et al.			03/05/92	
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	5,926,690	07/20/99	Toprac et al.			05/28/97	
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	5,943,237	08/24/99	Van Boxem			10/17/97	
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	5,961,369	10/05/99	Bartels et al.			06/04/98	
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	6,111,634	08/29/00	Pecen et al.			05/28/97	
	6,112,130	08/29/00	Fukuda et al.			10/01/97	
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	6,127,263	10/03/00	Parikh			07/10/98	
	6,128,016	10/03/00	Coelho et al.			12/20/96	
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				APPLICANT Alexander T. SCHWARM et al.					
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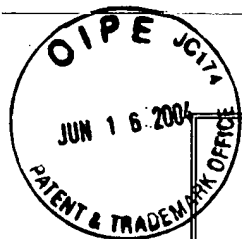
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APPLICANT
Alexander T. SCHWARM et al.

FILING DATE
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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		APPLICANT Alexander T. SCHWARM et al.	
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